



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SURFBOARDS®



THE BREADBOARDING MEDIUM FOR SURFACE MOUNT™

33000 SERIES APPLICATION SPECIFIC ADAPTERS

IDS33006
REV 1-2012

MODEL **33006**
6 LEAD .65 MM PITCH DEVICES

ACCEPTS
THESE
DEVICES



PARTIAL
LISTING

SC-70-6
SC-88 6 LEAD

SOT-363

ANALOG: KS-6

KEC: US6

LINEAR: SC6

MICREL: SC-70-6LD-LP-1

MOTOROLA: CASE No. 419B-01

PANASONIC: S mini 6-F1, S mini 6-G1

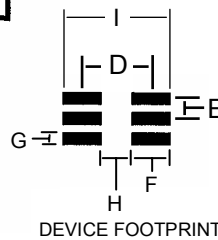
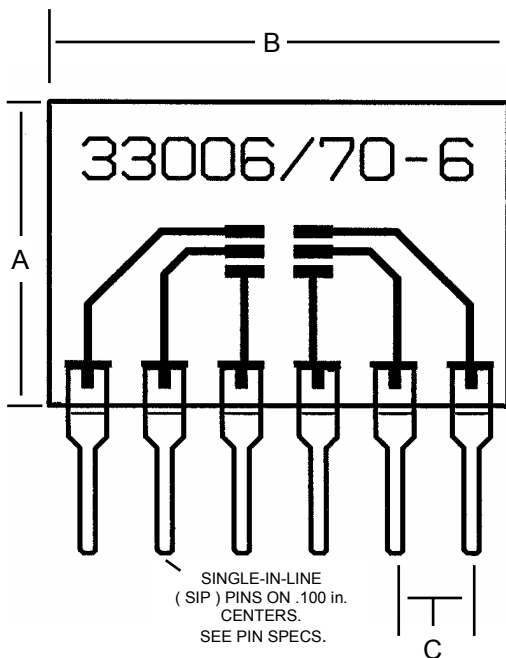
WS mini 6-F1

RENESAS: CMPAK-6

ROHM: TUMT6, UDM6, UMT6

T.I. DCK (R-PDSO-G6)

TOSHIBA: UF6, US6

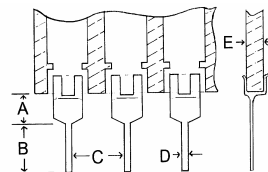


ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT

PINS ON .100 CENTERS PROVIDE
COMPATIBILITY WITH SOCKETS AND
BOTH STANDARD AND SOLDERLESS
BREADBOARDS.

FOR PROTOTYPING, DEVICE EVALUATION OR
TEST, SMD TO THROUGH HOLE
CONVERSION.

PIN SPECIFICATIONS / TOLERANCES



In Inches
A = .062 +/- .006
B = .130 +/- .010
C = .100 +/- .005
D = .020 +/- .004
E = .031 +/- .005

BOARD SPECIFICATIONS

BOARD MATERIAL: .8mm, +/- .13mm .031in +/- .005 in.
Thick G-10 FR-4 Glass Epoxy or equivalent.
CIRCUITS: 1 oz. Copper with RoHS compliant Lead
Free solder coating. Patten Position on board +/-
.5mm .020in.

TOLERANCES: If not noted are +/- 20%. Nominal values are given.
Controlling unit is Millimeters. Values rounded to nearest decimal. Slight
Variations due to manufacturing process can occur.

FIG.	INCHES	MM	NOTE:
A	.400	10.16	BOARD HEIGHT +/- .5mm .020in.
B	.600	15.24	BOARD WIDTH +/- .5mm .020in.
C	.100	2.54	SIP PIN SPACE +/- .20mm .008in.
D	.090	2.28	PAD CENTERLINE
E	.0256	.65	DEVICE LEAD PITCH
F	.050	1.27	PAD LENGTH
G	.015	.381	PAD WIDTH
H	.040	1.01	GAP
I	.140	3.55	MAX LEAD WIDTH



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